

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: **2002043554 A**

(43) Date of publication of application: **08.02.02**

(51) Int. Cl.

**H01L 27/14**

**H01L 21/60**

**H01L 23/02**

**H01L 23/12**

**H01L 31/02**

**H04N 5/335**

(21) Application number: **2000359731**

(22) Date of filing: **27.11.00**

(30) Priority: **17.07.00 TW 2000 89114388**

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**(54) CCD PACKAGE MODULE**

**(57) Abstract:**

PROBLEM TO BE SOLVED: To provide a CCD package module for reduced thickness.

SOLUTION: Related to a CCD package module 1, a circuit 121 is directly, chiefly, manufactured on the bottom surface of a glass 12 for package combination between an image-taking chip 11 and a flip chip, and a tin ball 13 is used for circuit combination between the circuit 121 and a printed circuit board 16. The thickness of a package module of the image-taking chip of a charge coupled device is reduced by coupling technology of the flip chip, use of a transparent glass substrate to manufacture a circuit for a package, or a coupling technology of the flip chip for combination with various substrate, for the package module of a thin-type CCD image-taking chip.

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